

MECHANICAL SPECIFICATIONS FOR CHIPBOARD ACCORDING TO EN-312

Particle board for interior fitments (including furniture, no structural boards) for use in wet conditions P3

CARACTERÍSTICAS CHARACTERISTIC	Unidades Units	Método de ensayo Test method	ESPEORES (mm) / THICKNESS (mm)							
			> 3 a 4	> 4 a 6	> 6 a 13	>13 a 20	>20 a 25	>25 a 32	>32 a 40	>40
- Resistencia a la flexión (Bending strength)	N/mm ²	EN 310	13	14	15	14	12	11	9	7,5
- Módulo de elasticidad en flexión (Modulus of Elasticity in Bending)	N/mm ²	EN 310	1800	1950	2050	1950	1850	1700	1550	1350
- Cohesión interna (internal bond)	N/mm ²	EN 319	0,5	0,5	0,45	0,45	0,4	0,35	0,30	0,25
- Hinchazón en grosor 24 h (Swelling in thickness, 24h)	%	EN 317	23	20	17	14	13	13	12	12

*Values for bending strength, internal bond and swelling thickness are referred to conditions of relative humidity of 65% and temperature of 20°C.

HUMIDITY RESISTANCE REQUIREMENTS ACCORDING TO EN-312

Particle boards (no structural boards) used in wet conditions P3

CARACTERÍSTICAS CHARACTERISTIC	Unidades Units	Método de ensayo Test method	ESPEORES (mm) / THICKNESS (mm)							
			> 3 a 4	> 4 a 6	> 6 a 13	>13 a 20	>20 a 25	>25 a 32	>32 a 40	>40
OPCIÓN 1/OPTION 1										
- Cohesión interna después de ensayo cíclico (internal bond after cyclic test)	N/mm ²	EN 321	0,18	0,18	0,15	0,13	0,12	0,10	0,09	0,08
- Hinchazón en grosor después de ensayo cíclico (swelling in thickness after cyclic test)	%	EN 321	15	14	14	13	12	12	11	11
OPCIÓN 2/OPTION 2										
- Cohesión interna después de ensayo de cocción (internal bond after boiling water test)	N/mm ²	EN 1087-1	0,09	0,09	0,09	0,08	0,07	0,07	0,06	0,06

*Values for internal bond and swelling in thickness after treatment according to option 1 (before the test) are referred to conditions of relative humidity of 65% and temperature of 20°C.
 **Values for internal bond and swelling in thickness after treatment according to option 2 (before the test) are referred to conditions of relative humidity of 65% and temperature of 20°C.